

# MC74AC32, MC74ACT32

## Quad 2-Input OR Gate

### Features

- Outputs Source/Sink 24 mA
- 'ACT32 Has TTL Compatible Inputs
- These Devices are Pb-Free and are RoHS Compliant

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	$V_{CC}$	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	$V_{in}$	-0.5 to $V_{CC}$ +0.5	V
DC Output Voltage (Referenced to GND)	$V_{out}$	-0.5 to $V_{CC}$ +0.5	V
DC Input Current, per Pin	$I_{in}$	$\pm 20$	mA
DC Output Sink/Source Current, per Pin	$I_{out}$	$\pm 50$	mA
DC $V_{CC}$ or GND Current per Output Pin	$I_{CC}$	$\pm 50$	mA
Storage Temperature	$T_{stg}$	-65 to +150	$^{\circ}C$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

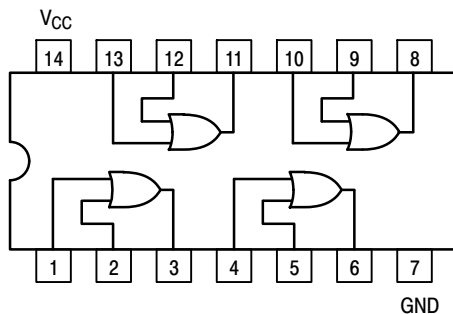
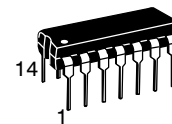


Figure 1. Pinout: 14-Lead Packages Conductors  
(Top View)

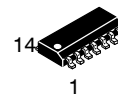


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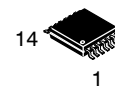
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PDIP-14  
N SUFFIX  
CASE 646



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G

### DEVICE MARKING INFORMATION

See specific marking information in the device marking section on page 5 of this data sheet.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MC74AC32, MC74ACT32

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V <sub>CC</sub>	Supply Voltage	'AC	2.0	5.0	6.0	V
		'ACT	4.5	5.0	5.5	
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)	0	-	V <sub>CC</sub>	V	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 3.0 V	-	150	-	ns/V
		V <sub>CC</sub> @ 4.5 V	-	40	-	
		V <sub>CC</sub> @ 5.5 V	-	25	-	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	10	-	ns/V
		V <sub>CC</sub> @ 5.5 V	-	8.0	-	
T <sub>J</sub>	Junction Temperature (PDIP)	-	-	140	°C	
T <sub>A</sub>	Operating Ambient Temperature Range	-40	25	85	°C	
I <sub>OH</sub>	Output Current – High	-	-	-24	mA	
I <sub>OL</sub>	Output Current – Low	-	-	24	mA	

- V<sub>in</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
- V<sub>in</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

## DC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	74AC		74AC		Unit	Conditions
			T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C			
			Typ	Guaranteed Limits				
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V	
		4.5	2.25	3.15	3.15			
		5.5	2.75	3.85	3.85			
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V	
		4.5	2.25	1.35	1.35			
		5.5	2.75	1.65	1.65			
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I <sub>OUT</sub> = -50 μA	
		4.5	4.49	4.4	4.4			
		5.5	5.49	5.4	5.4			
		3.0	-	2.56	2.46	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> -12 mA I <sub>OH</sub> -24 mA -24 mA	
		4.5	-	3.86	3.76			
		5.5	-	4.86	4.76			
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I <sub>OUT</sub> = 50 μA	
		4.5	0.001	0.1	0.1			
		5.5	0.001	0.1	0.1			
		3.0	-	0.36	0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 12 mA I <sub>OL</sub> 24 mA 24 mA	
		4.5	-	0.36	0.44			
		5.5	-	0.36	0.44			
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V <sub>I</sub> = V <sub>CC</sub> , GND	
I <sub>OLD</sub>	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max	
I <sub>OHD</sub>		5.5	-	-	-75	mA	V <sub>OHD</sub> = 3.85 V Min	
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	4.0	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND	

\*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I<sub>IN</sub> and I<sub>CC</sub> @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V<sub>CC</sub>.

# MC74AC32, MC74ACT32

## AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V <sub>CC</sub> * (V)	74AC			74AC		Unit	Fig. No.
			T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF			T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF			
			Min	Typ	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay	3.3 5.0	1.5 1.5	7.0 5.5	9.0 7.5	1.5 1.0	10.0 8.5	ns	3-5
t <sub>PHL</sub>	Propagation Delay	3.3 5.0	1.5 1.5	7.0 5.0	8.5 7.0	1.0 1.0	9.0 7.5	ns	3-5

\*Voltage Range 3.3 V is 3.3 V ±0.3 V.  
Voltage Range 5.0 V is 5.0 V ±0.5 V.

## DC CHARACTERISTICS

Symbol	Parameter	V <sub>CC</sub> (V)	74ACT		74ACT	Unit	Conditions
			T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		
			Typ	Guaranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5	1.5	2.0	2.0	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
		5.5	1.5	2.0	2.0		
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5	1.5	0.8	0.8	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
		5.5	1.5	0.8	0.8		
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5	4.49	4.4	4.4	V	I <sub>OUT</sub> = -50 μA
		5.5	5.49	5.4	5.4		
		4.5	-	3.86	3.76	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>OH</sub> = -24 mA -24 mA
		5.5	-	4.86	4.76		
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5	0.001	0.1	0.1	V	I <sub>OUT</sub> = 50 μA
		5.5	0.001	0.1	0.1		
		4.5	-	0.36	0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> I <sub>OL</sub> = 24 mA 24 mA
		5.5	-	0.36	0.44		
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V <sub>I</sub> = V <sub>CC</sub> , GND
ΔI <sub>CCT</sub>	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	-	1.5	mA	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V
I <sub>OLD</sub>	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>		5.5	-	-	-75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	4.0	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND

\*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

## MC74AC32, MC74ACT32

**AC CHARACTERISTICS** (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V <sub>CC</sub> * (V)	74ACT			74ACT		Unit	Fig. No.
			T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF			T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF			
			Min	Typ	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–6
t <sub>PHL</sub>	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–6

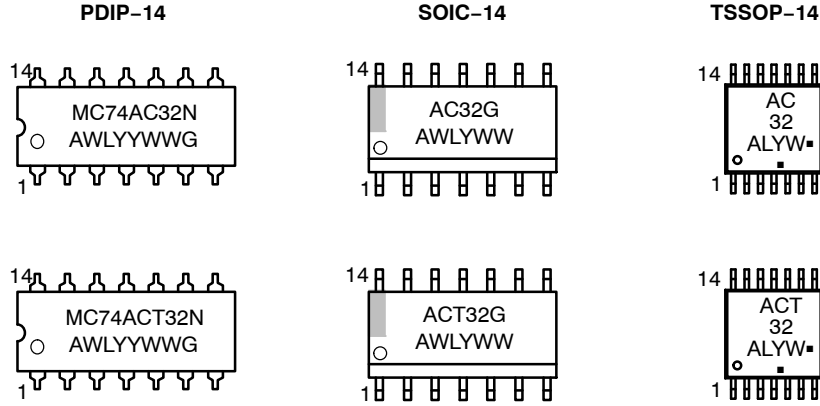
\*Voltage Range 5.0 V is 5.0 V ±0.5 V.

### CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	20	pF	V <sub>CC</sub> = 5.0 V

# MC74AC32, MC74ACT32

## MARKING DIAGRAMS



A = Assembly Location  
 L, WL = Wafer Lot  
 Y, YY = Year  
 W, WW = Work Week  
 G = Pb-Free Package  
 ▪ = Pb-Free Package  
 (Note: Microdot may be in either location)

## ORDERING INFORMATION

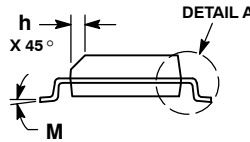
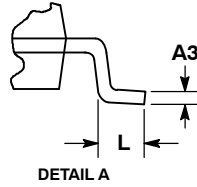
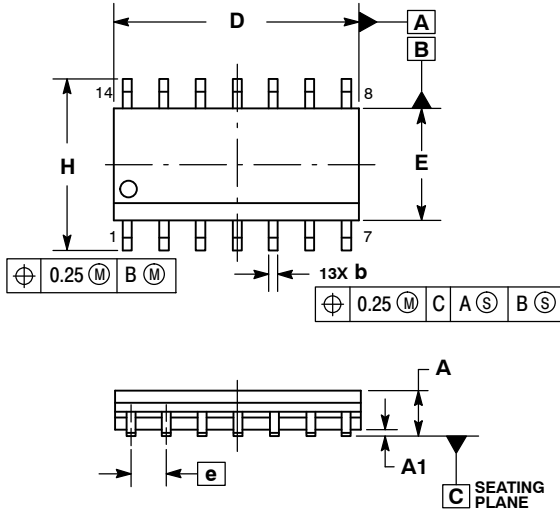
Device	Package	Shipping†
MC74AC32NG	PDIP-14 (Pb-Free)	25 Units / Rail
MC74ACT32NG	PDIP-14 (Pb-Free)	
MC74AC32DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74AC32DR2G	SOIC-14 (Pb-Free)	2500 Units / Reel
MC74ACT32DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74ACT32DR2G	SOIC-14 (Pb-Free)	2500 Units / Reel
MC74AC32DTR2G	TSSOP-14 (Pb-Free)	
MC74ACT32DTR2G	TSSOP-14 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MC74AC32, MC74ACT32

## PACKAGE DIMENSIONS

SOIC-14 NB  
CASE 751A-03  
ISSUE K

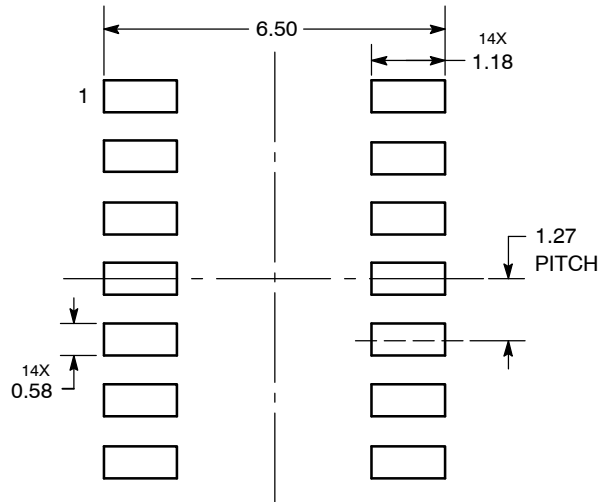


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

### SOLDERING FOOTPRINT\*



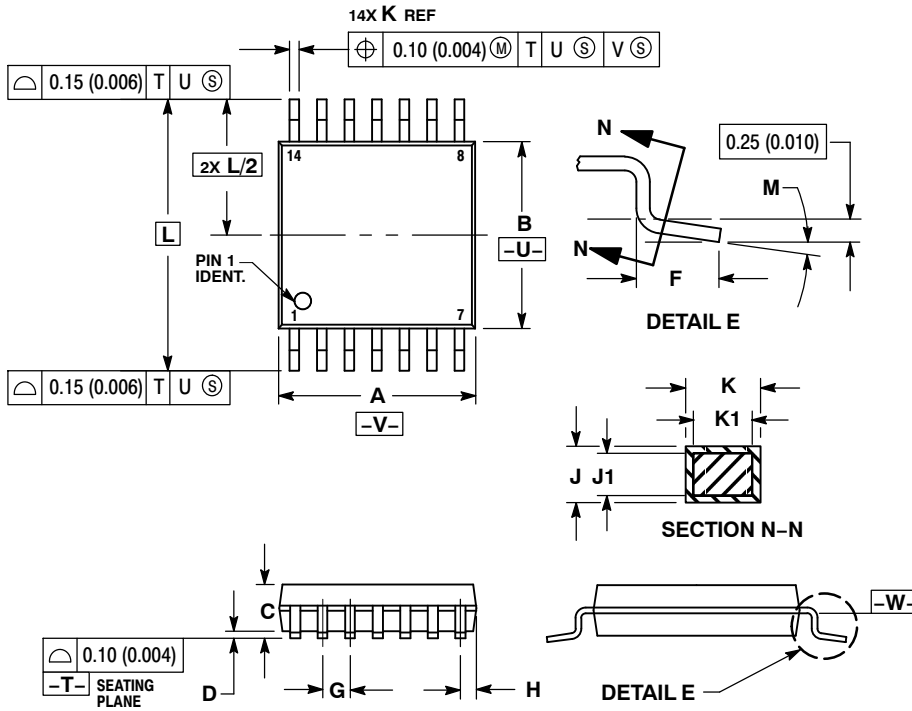
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74AC32, MC74ACT32

## PACKAGE DIMENSIONS

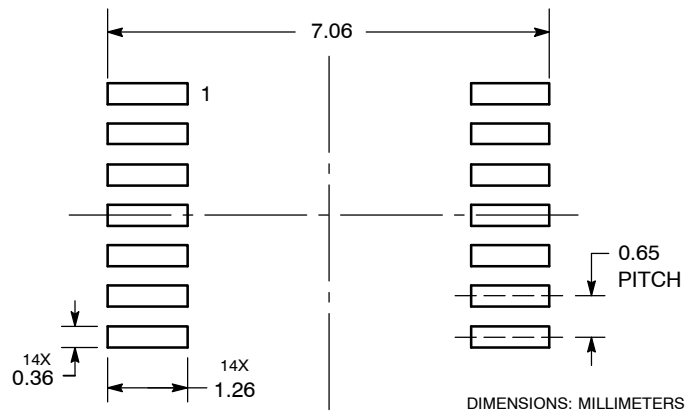
TSSOP-14  
CASE 948G-01  
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0° 8°		0° 8°	

### SOLDERING FOOTPRINT\*

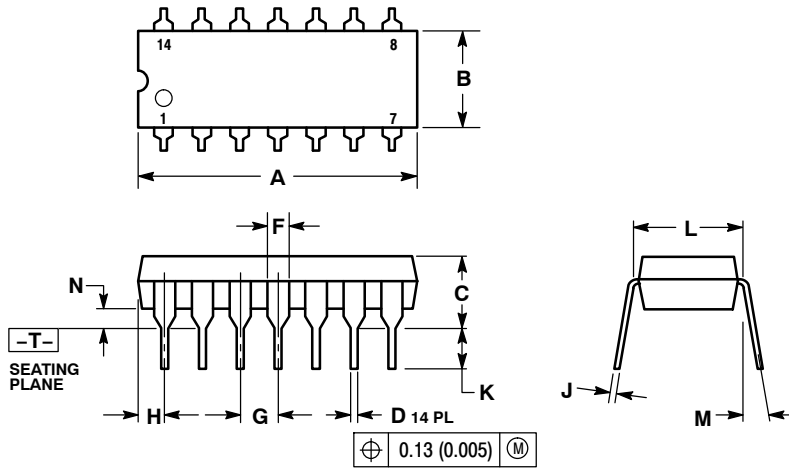


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MC74AC32, MC74ACT32

## PACKAGE DIMENSIONS

**PDIP-14**  
CASE 646-06  
ISSUE P



### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

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